



Material Content Data Sheet



Sales Product Name	IAUA120N04S5N014	Issued	12. May 2021
MA#	MA001697376		
Package	PG-HSOF-5-2	Weight*	368.23 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.077	0.29	0.29	2924	2924
leadframe	inorganic material	phosphorus	7723-14-0	0.015			40	
	non noble metal	iron	7439-89-6	0.048	0.01		132	
	non noble metal	copper	7440-50-8	48.418	13.15	13.16	131489	131661
wire	noble metal	gold	7440-57-5	0.052	0.01	0.01	141	141
encapsulation	inorganic material	zincoxide	1314-13-2	1.424	0.39		3866	
	miscellaneous	miscellaneous	-	5.695	1.55		15465	
	plastics	epoxy resin	-	21.355	5.80		57995	
	inorganic material	silicondioxide	60676-86-0	113.895	30.93	38.67	309307	386633
leadfinish	non noble metal	tin	7440-31-5	3.673	1.00	1.00	9975	9975
plating	noble metal	silver	7440-22-4	0.015			41	41
	non noble metal	tin	7440-31-5	0.030	0.01		80	
solder	noble metal	silver	7440-22-4	0.037	0.01		100	
	non noble metal	lead	7439-92-1	1.410	0.38	0.40	3829	4009
	inorganic material	phosphorus	7723-14-0	0.008			23	
heat sink clip	non noble metal	iron	7439-89-6	0.028	0.01		77	
	non noble metal	copper	7440-50-8	28.224	7.66	7.67	76648	76748
	inorganic material	phosphorus	7723-14-0	0.043	0.01		116	
heatspreader	non noble metal	iron	7439-89-6	0.143	0.04		388	
	non noble metal	copper	7440-50-8	142.638	38.75	38.80	387364	387868
	*deviation	< 10%			Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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